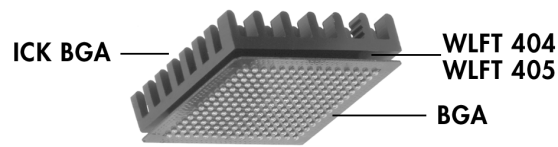


Heatsinks for PGAs and BGAs


- particularly suited for **B**all **G**rid **A**rrays
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component

art. no. ICK BGA 10 x 10 WLF ... 10 x 10		
art. no. ICK BGA 10 x 10 x 10 WLF ... 10 x 10		
art. no. ICK BGA 14 x 14 WLF ... 14 x 14		
art. no. ICK BGA 14 x 14 x 10 WLF ... 14 x 14		
art. no. ICK BGA 21 x 21 WLF ... 21 x 21		

B 13

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7